

09-17-1999

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LETTER



Attorney Docket No.: 008651-20007

101174133

To the Assistant Commission,

the enclosed original documents or copy thereof.

1. Name of conveying party(ies):

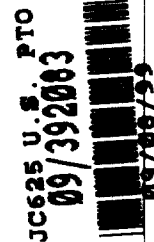
Hideo Yamagishi  
Toshihide Ohkatsu  
Masataka Kondo

Additional name(s) of conveying party(ies) attached? ☒ No

2. Name and address of receiving party(ies):

KANEKA CORPORATION  
2-4, Nakanoshima 3-chome  
Kita-ku, Osaka 530-8288, Japan

Additional name(s) & address(es) attached? ☒ No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: August 24, 1999

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

John P. Scherlach, Esq.  
LOEB & LOEB LLP  
10100 Santa Monica Blvd., 22nd Floor  
Los Angeles, CA 90067-4164

6. Total number of applications and patents involved: [ 1 ]

7. Total fee (37 CFR 3.41) \$40

☒ Enclosed  
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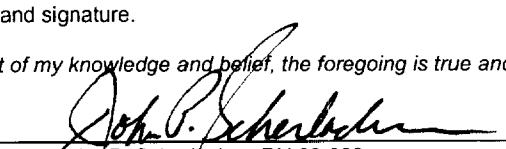
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9. Statement and signature.

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

  
John P. Scherlach, RN 23,009

Date: September 8, 1999

OMB No. 0651-0011 (exp. 4/94)

Mail documents to be recorded with required cover sheet information to:

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Assistant Commissioner for Patents  
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## A S S I G N M E N T

In consideration of value received, I, having a residence and post office address as stated below next to my name, the sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are listed below) of an invention described in an application for United States patent entitled:

## SOLAR CELL MODULE

said application having been filed on  
and assigned Serial No. ;  
sell and assign to  
KANEKA CORPORATION  
a corporation of Japan, having a business address at  
2-4, Nakanoshima 3-chome, Kita-ku, Osaka-shi, Osaka 530-8288 Japan

its successors, assigns or nominees, hereinafter referred to as  
"Assignee", my entire right, title and interest in and to said invention  
as disclosed, shown and described in said application for United States  
patent: (check one)

☒ executed concurrently herewith:

☐ executed separately herefrom:

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Loeb and Loeb LLP, 10100 Santa Monica Boulevard, Suite 2200,  
Los Angeles, California 90067-4164.

PATENT

REEL: 010237 FRAME: 0185

# A S S I G N M E N T

99S0342-1

Inventor: (Signature)

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